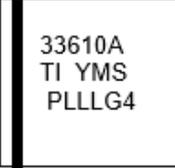
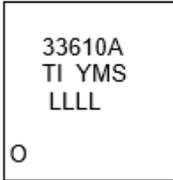


PCN Number:	20230217003.1A		PCN Date:	March 16, 2023												
Title:	Qualify TI Mexico as an additional Assembly site for select devices															
Customer Contact:	PCN Manager	Dept:	Quality Services													
Proposed 1st Ship Date:	May 17, 2023	Sample requests accepted until:	Apr 17, 2023*													
*Sample requests received after Apr 17, 2023 will not be supported.																
Change Type:																
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site											
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material											
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process											
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site											
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials											
				<input type="checkbox"/>	Wafer Fab Process											
PCN Details																
Description of Change:																
<p>Revision A is to announce the <u>addition</u> of new devices that was not included on the original PCN notification. The new devices are highlighted and bolded in the device list below. The expected first shipment date for the new device will be 90 days from this notice (June 17, 2023) for the newly added device only. The proposed 1st ship date of May 17, 2023 still applies for the original set of devices.</p>																
<p>Texas Instruments is pleased to announce the qualification of TI Mexico as an additional Assembly site for the list of devices shown below. Material differences between sites as follows.</p>																
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin</th> <th>Assembly Country Code</th> <th>Assembly City</th> </tr> </thead> <tbody> <tr> <td>ASESH</td> <td>ASH</td> <td>CHN</td> <td>Shanghai</td> </tr> <tr> <td>TI Mexico</td> <td>MEX</td> <td>MEX</td> <td>Aguascalientes</td> </tr> </tbody> </table>					Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly City	ASESH	ASH	CHN	Shanghai	TI Mexico	MEX	MEX	Aguascalientes
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly City													
ASESH	ASH	CHN	Shanghai													
TI Mexico	MEX	MEX	Aguascalientes													
Material Differences:																
	ASESH	TI Mexico														
Mount compound	EY1000063	4147858														
Mold Compound	EN2000509, EN20000519	4211880														
Package Marking differences:																
	ASESH	TI Mexico														
Pin One ID	Stripe	Dimple														
ECAT value	With	Without														

Example	 <p>33610A TI YMS PLLLG4</p>	 <p>33610A TI YMS LLLL O</p>
	<p>TI = TI LETTERS YM = YEAR MONTH DATE CODE LLL = ASSEMBLY LOT CODE S = ASSEMBLY SITE CODE P = SECONDARY SITE CODE G4 = ECAT █ = PIN 1 STRIPE</p>	<p>TI = TI LETTERS YM = YEAR MONTH DATE CODE LLLL = ASSEMBLY LOT CODE S = ASSEMBLY SITE CODE O = PIN 1 INDICATOR</p>

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change			

Changes to product identification resulting from this PCN:

Assembly Site		
ASESH	Assembly Site Origin (22L)	ASO: ASH
TI Mexico	Assembly Site Origin (22L)	ASO: MEX

Sample product shipping label (not actual product label)



TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 / 260C / 1 YEAR SEAL DT
MSL 1 / 235C / UNLIM 03 / 29 / 04
OPT:
ITEM: 39
LBL: 5A (L)T0:1750

G4



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected

LMR33610ADDAR	SN1101003DDAR	TPS54329DDAR	TPS54531DDAR
LMR33610BDDAR	SN1101004DDAR	TPS54329EDDA	TPS54627DDA
LMR33620ADDA	SN1101005DDAR	TPS54329EDDAR	TPS54627DDAR
LMR33620ADDAR	SN1706004DDA	TPS54335ADDA	TPS54628DDA
LMR33620BDDA	SN1706004DDAR	TPS54335ADDAR	TPS54628DDAR
LMR33620BDDAR	SN1708001DDAR	TPS54336ADDA	TPS56428DDA
LMR33620CDDA	SN54528DDAR	TPS54336ADDAR	TPS56428DDAR
LMR33620CDDAR	TPS54227DDA	TPS54427DDA	TPS56527DDAR
LMR33630ADDA	TPS54227DDAR	TPS54427DDAR	TPS56528DDA
LMR33630ADDAR	TPS54228DDA	TPS54428DDA	TPS56528DDAR
LMR33630BDDA	TPS54228DDAR	TPS54428DDAR	TPS56628DDA

LMR33630BDDAR	TPS54327DDA	TPS54527DDA	TPS56628DDAR
LMR33630CDDA	TPS54327DDAR	TPS54527DDAR	
LMR33630CDDAR	TPS54328DDA	TPS54528DDA	
LMR33640ADDAR	TPS54328DDAR	TPS54528DDAR	
LMR33640DDDAR	TPS54329DDA	TPS54531DDA	

Qualification Report

Approve Date 19-Jan-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LMR33610ADDAR	Qual Device: TPS54335ADDAR	Qual Device: TPS54531DDAR	QBS Reference: LMR16020PDDAR	QBS Reference: DRV8251DDAR	QBS Reference: LM5169FQDDARQ1
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-	-	-	3/231/0
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	3/231/0	-	-	3/231/0	3/231/0	-
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	1/77/0	-	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	1/77/0	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	1/77/0
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	3/228/0	1/76/0	1/76/0	3/228/0	3/228/0	3/90/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	3/228/0	1/76/0	1/76/0	3/228/0	3/228/0	3/90/0

SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB Solder;	-	-	-	-	-	3/66/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	3/66/0	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	3/30/0	1/10/0	1/10/0	3/30/0	3/30/0	3/30/0
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	-	1/3/0	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	4000 Volts	-	-	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/6/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0	1/30/0	1/30/0	3/90/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	-	3/90/0

QBS: Qual By Similarity

Qual Device LMR33610ADDAR is qualified at MSL2 260C

Qual Device TPS54335ADDAR is qualified at MSL2 260C

Qual Device TPS54531DDAR is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	PCN_ww_admin_team@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your

application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disdaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.